Packaging Material, Package Produced Therefrom And Method For Constructing the Package

Abstract of Disclosure

The present invention provides packaging material for making packages, comprising a breakable film; and a substrate on which the breakable film is positioned, wherein the substrate comprises a chemically resistant and non-heat sealable (NHS) layer having a first surface and a second surface, and a heat sealable (HS) layer bonded to the first surface of the NHS layer, and the breakable film is laminated onto the second surface of the NHS layer, and wherein at least one die cut line to define a preformed hole is formed through the NHS and HS layers. The invention also provides a package produced therefrom and a method for constructing the package.

Fig. 10